KYOCERA KE-300TS-1

Epoxy; Epoxide

KYOCERA Chemical Corporation

Message:

High Reliable and Easy-to-Use Molding Compounds for Various Type of Packages
Strong Points
Provide Various Molding Compounds with High Reliability to Cover Many Applications such as LSI, Transistors and Diodes.
Good Curability and Applicable to Various Molding Machines (Both Automated and Conventional)
Low Stress of Large chips and Applicable to Encapsulation.
Application
Smaller SOP, Smaller QFP, DIP, SIP/ZIP, TO-PKG, DPAK, SOT, Unbalanced PKG, Module

General Information		
Uses	Electrical/Electronic Applications	
Physical	**Nominal Value**	**Unit**
Specific Gravity	1.80	g/cm³
Spiral Flow	90.0	cm
Mechanical	**Nominal Value**	**Unit**
Flexural Modulus	12500	MPa
Flexural Strength	140	MPa
Thermal	**Nominal Value**	**Unit**
Glass Transition Temperature	165	°C
CLTE - Flow		
-- [1]	1.8E-5	cm/cm/°C
-- [2]	6.5E-5	cm/cm/°C
Uncured Properties	**Nominal Value**	**Unit**
Gel Time	0.50	min
NOTE		
1.	Alpha 1	
2.	Alpha 2	

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